

Abstract

Method, device, computer-readable storage medium and computer program element for the monitoring of a manufacturing process of a plurality of physical objects

In the case of the method, an analysis is performed by using values of at least one process parameter of the manufacturing process of the physical object and, as a result of the analysis, when they satisfy a prescribed selection criterion, physical objects are marked in such a way that the associated physical objects can be taken as a random sample for the monitoring of the manufacturing process.

List of designations

100 schematic block diagram of a setup of a semiconductor production installation
101 block of an overall manufacturing process
102 block of a first production area
103 block of a second production area
104 block of a third production area
105 block of a fourth production area
200 semiconductor chip production installation
201 multiplicity of semiconductor chip production sub-installations
202 path of a wafer or a lot through the semiconductor chip production installation
201 machine
301 sensor
302 SECS interface
303 PDSF file
304 log file
306 local communication network (LAN)
307 memory
308 evaluation unit
409 mean value of the misalignment values of a lot
410 variation of the distribution
411 wafer close to the mean value of the distribution
412 wafer at the maximum distance from the mean value
413 wafer at the border of the 1σ range of the distribution